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U.S. DEPARTMENT OF COMMER(
Patent and Trademark Offi

ATTOR	VEY	DOC	KET	NO ·
1111010	12.			

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural name: are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

PRESSURE-SENSITIVE ADHESION SHEETS FOR SILICONE OXIDE-CONTAINING MATERIAL

the specification of which:			
is attached hereto; or			
was filed as United States application Serial No			
was filed as PCT international application Number (if applicable).	on	and was amended under	PCT Article 19

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by amy amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office information which is material to the patentability of claims presented in this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) or §365(b) of any foreign application(s) for pater or inventor's certificate or §365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT internation application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed:

	PRIOR FOREIGN A	PPLICATION(S):		
COUNTRY (if PCT, indicate PCT)	APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORI	TY CLAIMED
Japan	P. Hei. 9-346124	16,12,1997	[X] Yes	[] No
Japan	P. Hei. 9-353102	22,12,1997	[X] Yes	[] No
			[] Yes	[] No
			[] Yes	[] No

Combined Declaration For Patent A (includes Reference to PCT Interna		•	ORNEY DOCKET N	O.;
I hereby claim the benefits listed below.	under Title 35, United States (Code §119(e) of any Un	ited States provisional	application(s)
	U.S. PROVISIO	NAL APPLICATIONS		
U.S. PROVISIONAL AF	PLICATION NO.	U.S. FILING DATE		
		<u> </u>		
<u> </u>				
PCT international application subject matter of each of the provided by the first parage Patent and Trademark Officapplication in accordance with date of the prior application	ander Title 35, United States Co ion(s) designating the United States of the claims of this application is reaph of Title 35, United States of the all information known to me with Title 37, Code of Federal In(s) and the national or PCT into	tates of America that is/ not disclosed in that/tho: Code, §112, I acknowle e to be material to the pa Regulations, §1.56 whic ternational filing date of	are listed below and, in se prior application(s) dge the duty to discloss atentability of claims ph became available bef this application:	nsofar as the in the manner se to the U.S. presented in this tween the filing
PRIOR U.S. APPLICATI	ONS OR PCT INTERNATIO	NAL APPLICATIONS	······································	
0.0.11112101		STATUS (Check One)		
U.S. APPLICATION NO.	U.S. FILING DATE	PATENTED	PENDING	ABANDONED
	 			
<u></u>				
Bockius LLP included in the	. Y: As a named inventor, I here ne Customer Number provided k Office connected therewith, a	below to prosecute this	application and to tran	sact all business
Direct Telephone Calls To: (name and telephone number)				
		hael Thesz 467-7658		

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

FULL NAME OF SOLE OR FIRST INVENTOR	Katsunari Oji		
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FIRST OR SOLE INVENTO	or's signature Katsunari Osi	DATE December 9, 199	
FULL NAME OF SECOND INVENTOR	Yoshinao Kitamura		
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SECOND INVENTOR'S SIGNATURE Yoshinao Kitamura DATE December 9,			
FULL NAME OF THIRD INVENTOR	Takao Yoshikawa		
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THIRD INVENTOR'S SIGNATURE Jakao Yoshikawa Date December 9, 19			

Listing of Inventors Continued on attached page(s) [] Yes [X] No

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention						
	entitled:	GTATGOND ONTDE CONTAINT	TO MATERIAL			
	PRESSURE-SENSITIVE ADHESION SHEET		NG PIATERIAL			
	for which I/WE executed an application for United States Letters Patent concurrently herewith; or on December 9, 1998; or filed an application for United States Letters Patent on , (Serial No); and					
. 1	WHEREAS, NITTO DENKO COR	PORATION	,			
	a corporation of Japan 1-2, Shimohozumi 1-chome, Ibarak	, whose post office	address is			
	1-2, Shimohozumi 1-chome, Ibarak	<u>i-shi, Osaka, Japan</u> (hereina	fter referred to as Assignee),			
	is desirous of securing the entire right, title, and interes	it in and to this invention, the application	for United States Letters			
	Patent on this invention and the Letters Patent to be is	sue upon this application;				
South Beat the real with the work it willer than that it	NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in Jaccordance with the terms of this Assignment; AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns. AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of					
. 1	Attorney in this application, to insert here in parenthese	es (Application No, fil	led)			
the filing date and application number of said application when known.						
	IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).					
:	1. Full Name of Sole of First Assignor	Assignor's Signature	Date			
	Katsunari Oji	Katsunari Bis	December 9, 1998			
.*			Citizenship			
	Address Osaka, Japan		Japan			
Obuna, oupan			_			
	2. Full Name of Second Assignor	Assignor's Signature Yoshinao Kitamusa	Date 1 0000			
	Yoshinao Kitamura	yoshinao kulamasa	December 9, 1998			
	Address Osaka, Japan	•	Citizenship Japan			

MORGAN, LEWIS & BOCKIUS